

TinPlate

Electroless mat tin plating for printed circuit boards

FEATURES

Simple immersion plating for copper-clad printed circuit boards

Produces mat tin coating ideal for both lead-based and lead-free soldering processes

Permanent, adherent, pure tin plating with no organic brighteners to cause soldering problems

Room temperature plating process

Quick – one minute plating

APPLICATION

Apply to any copper-clad surface by immersion at room temperature. Leave for one minute then take out and rinse briefly in flowing water. Plating thickness will depend on the surface state of copper with typical thickness of around ½ micron (0.02 mil). For best results, it is advisable to clean the copper surface before plating with a good copper cleaner such as SolderClean from ElectrosPELL. Used plating agent can be returned to the original container for later use until exhausted. Please note that the solderability of tinned surfaces degrades over time thus it is best to solder tin-plated surfaces within two days of immersion plating.

AVAILABILITY

Available in 500 ml white HDPE bottles and in 5 litre cans for bulk use.